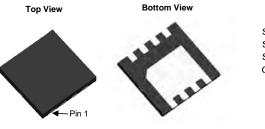
## NTTFS5826NLTAG

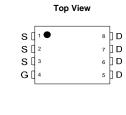


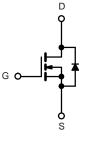
## N-Channel 60 V (D-S) MOSFET

| PRODUCT SUMMARY     |                                  |                                 |  |
|---------------------|----------------------------------|---------------------------------|--|
| V <sub>DS</sub> (V) | R <sub>DS(on)</sub> (Ω)          | I <sub>D</sub> (A) <sup>a</sup> |  |
| 60                  | 0.010 at V <sub>GS</sub> = 10 V  | 15                              |  |
|                     | 0.013 at V <sub>GS</sub> = 4.5 V | 12                              |  |

#### DFN 3x3 EP







N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> =                      | = 25 °C, unless othe    | rwise noted)                      |                                      |    |
|---|-------------------------|-----------------------------------|--------------------------------------|----|
| Parameter   | Symbol                  | Limit                             | Unit                                 |    |
| Gate-Source Voltage   |                         | V <sub>GS</sub>                   | ± 20                                 | V  |
|   | T <sub>C</sub> = 25 °C  |                                   | 15                                   |    |
| Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup> | T <sub>C</sub> = 100 °C |                                   | 13 <sup>a</sup>                      |    |
| Pulsed Drain Current  | I <sub>DM</sub>         | 100                               | А                                    |    |
| Continuous Source Current (Diode Conduction)                    | ۱ <sub>S</sub>          | 50 <sup>a</sup>                   |                                      |    |
| Avalanche Current   | I <sub>AS</sub>         | 50                                |                                      |    |
| Single Avalanche Energy (Duty Cycle $\leq$ 1 %)                 | L = 0.1 mH              | E <sub>AS</sub>                   | 125                                  | mJ |
| Maximum Dawar Dissinction                                       | T <sub>C</sub> = 25 °C  | Р                                 | 136                                  | w  |
| Maximum Power Dissipation                                       | T <sub>A</sub> = 25 °C  | • P <sub>D</sub>                  | 3 <sup>b</sup> , 8.3 <sup>b, c</sup> | vv |
| Operating Junction and Storage Temperature Range                |                         | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 175                          | °C |

| THERMAL RESISTANCE RATINGS               |                        |                   |         |         |      |  |
|--|------------------------|-------------------|---------|---------|------|--|
| Parameter                                |                        | Symbol            | Typical | Maximum | Unit |  |
| Mariana lunation to Ambianta             | $t \le 10 \text{ sec}$ | R <sub>thJA</sub> | 15      | 18      |      |  |
| Maximum Junction-to-Ambient <sup>a</sup> | Steady State           |                   | 40      | 50      | °C/W |  |
| Maximum Junction-to-Case                 |                        | R <sub>thJC</sub> | 0.85    | 1.1     |      |  |

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. t  $\leq$  10 s.

| / <sub>DS</sub> (V) | R <sub>DS(on)</sub> (Ω)        |
|---------------------|--------------------------------|
| 60                  | 0.010 at V <sub>GS</sub> = 10  |
| 00                  | 0.013 at V <sub>GS</sub> = 4.5 |
|                     |                                |

#### **FEATURES**

- 175 °C Junction Temperature
- TrenchFET<sup>®</sup> Power MOSFET
- Material categorization:



| B     | ®<br>VBsemi |
|-------|-------------|
| www.\ | /Bsemi.com  |

| Parameter                                     | Symbol              | Test Conditions   | Min.    | Typ. <sup>a</sup> | Max.       | Unit |  |
|---|---------------------|---|---------|-------------------|------------|------|--|
| Static  | Symbol              | Test conditions   | 141111. | Typ."             |            | Unit |  |
| Drain-Source Breakdown Voltage                | V <sub>DS</sub>     | V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 µA  | 60      |                   |            |      |  |
| 3   | -                   | 66 5 1  |         | 2                 | 3          | V    |  |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub> |   |         | 2                 | -          |      |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>    | $V_{DS} = 0 V, V_{GS} = \pm 20 V$   |         |                   | ± 100      | nA   |  |
|   |                     | $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$   |         |                   | 1<br>50 μΑ |      |  |
| Zero Gate Voltage Drain Current               | IDSS                | $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$                       |         |                   |            |      |  |
|   |                     | $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 \text{ °C}$                       |         |                   | 250        |      |  |
| On-State Drain Current <sup>b</sup>           | I <sub>D(on)</sub>  | $V_{DS} = 5 V, V_{GS} = 10 V$   | 60      |                   |            | A    |  |
|   |                     | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A   |         | 0.010             |            |      |  |
| Drain-Source On-State Resistance <sup>b</sup> | R <sub>DS(on)</sub> | $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}, \text{ T}_{J} = 125 ^{\circ}\text{C}$ |         | 0.016             |            | Ω    |  |
| Diam-Source On-State Resistance               | "DS(on)             | $V_{GS}$ = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C                             |         | 0.020             |            |      |  |
|   |                     | $V_{GS} = 4.5 \text{ V}, I_{D} = 15 \text{ A}$  |         | 0.013             |            |      |  |
| Forward Transconductance <sup>b</sup>         | 9 <sub>fs</sub>     | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A   |         | 60                |            | S    |  |
| Dynamic                                       | -                   |   |         |                   |            |      |  |
| Input Capacitance                             | C <sub>iss</sub>    |   |         | 2650              |            |      |  |
| Output Capacitance                            | C <sub>oss</sub>    | $V_{GS}$ = 0 V, $V_{DS}$ = 25 V, f = 1 MHz  |         | 470               |            | pF   |  |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>    |   |         | 225               |            | 1    |  |
| Total Gate Charge <sup>c</sup>                | Qg                  |   |         | 47                | 70         |      |  |
| Gate-Source Charge <sup>c</sup>               | Q <sub>gs</sub>     | $V_{DS}$ = 30 V, $V_{GS}$ = 10 V, $I_{D}$ = 50 A  |         | 10                |            | nC   |  |
| Gate-Drain Charge <sup>c</sup>                | Q <sub>gd</sub>     |   |         | 12                |            |      |  |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>  |   |         | 10                | 20         |      |  |
| Rise Time <sup>c</sup>                        | tr                  | $V_{DD} = 30 \text{ V}, \text{ R}_{L} = 0.6 \Omega$   |         | 15                | 25         | ns   |  |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub> | $I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$                          |         | 35                | 50         |      |  |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>      |   |         | 20                | 30         |      |  |
| Source-Drain Diode Ratings and Cha            | aracteristics (     | T <sub>C</sub> = 25 °C)   | •       |                   | <u> </u>   |      |  |
| Pulsed Current                                | I <sub>SM</sub>     |   |         |                   | 60         | А    |  |
| Diode Forward Voltage                         | V <sub>SD</sub>     | $I_{F} = 20 \text{ A}, V_{GS} = 0 \text{ V}$  |         | 1                 | 1.5        | V    |  |
| Reverse Recovery Time                         | t <sub>rr</sub>     | I <sub>F</sub> = 20 A, di/dt = 100 A/μs   |         | 45                | 100        | ns   |  |
|   |                     |   |         |                   |            |      |  |

#### **SPECIFICATIONS** (T<sub>1</sub> = 25 °C, unless otherwise noted)

Notes:

a. For design aid only; not subject to production testing.

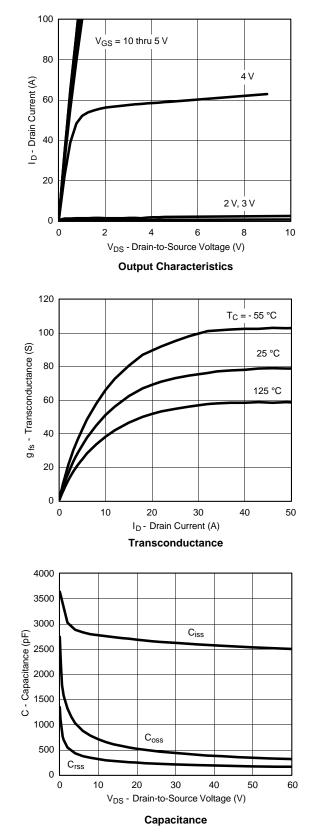
b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

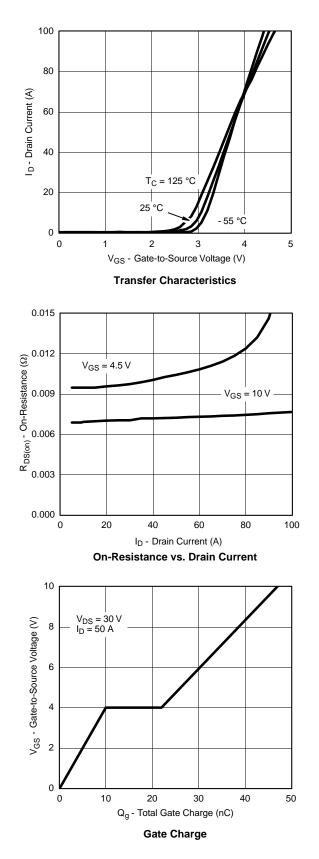
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



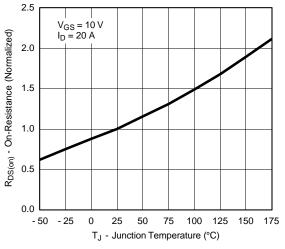
#### TYPICAL CHARACTERISTICS (25 °C unless noted)



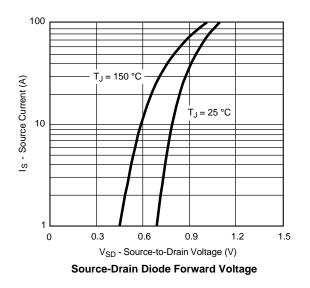




#### TYPICAL CHARACTERISTICS (25 °C unless noted)



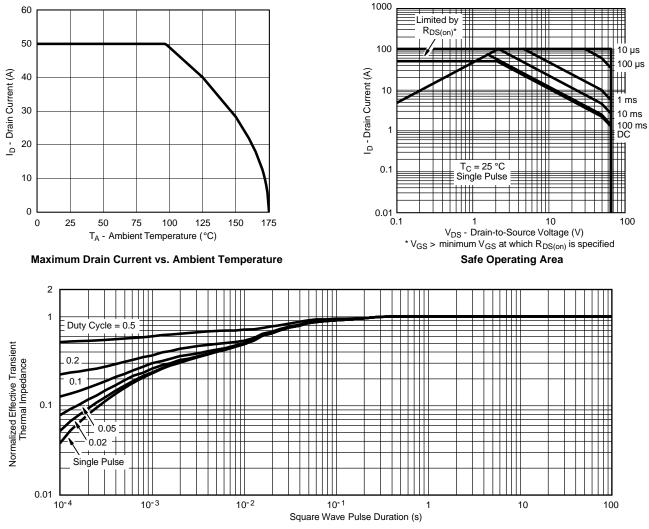
**On-Resistance vs. Junction Temperature** 



### NTTFS5826NLTAG

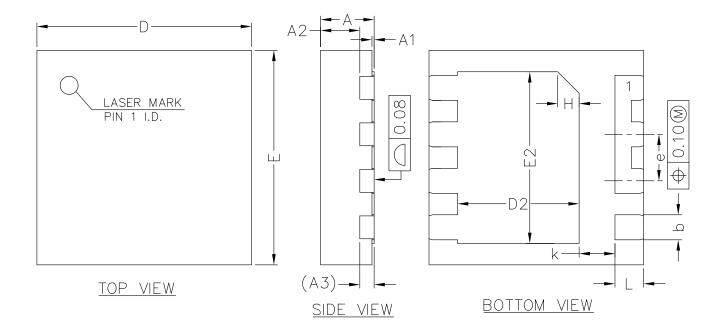


#### **THERMAL RATINGS**



Normalized Thermal Transient Impedance, Junction-to-Case







<u>SIDE VIEW</u>

| SYMBOL | MIN     | NOM  | МАХ  |  |
|--------|---------|------|------|--|
| А      | 0.70    | 0.75 | 0.80 |  |
| A1     | 0.00    | 0.02 | 0.05 |  |
| A2     | 0.50    | 0.55 | 0.60 |  |
| A3     | 0.20REF |      |      |  |
| b      | 0.30    | 0.35 | 0.40 |  |
| D      | 2.90    | 3.00 | 3.10 |  |
| E      | 2.90    | 3.00 | 3.10 |  |
| D2     | 1.60    | 1.70 | 1.80 |  |
| E2     | 2.30    | 2.40 | 2.50 |  |
| е      | 0.55    | 0.65 | 0.75 |  |
| К      | 0.40    | 0.50 | 0.60 |  |
| L      | 0.35    | 0.40 | 0.45 |  |

# COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)



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